US008363859B2

(12) United States Patent
Chen

(10) **Patent No.: US 8,363,859 B2**
(45) **Date of Patent: Jan. 29, 2013**

(54) **MICROELECTROMECHANICAL SYSTEM MICROPHONE PACKAGE STRUCTURE**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **13/446,651**

(22) Filed: **Apr. 13, 2012**

(65) **Prior Publication Data**

US 2012/0193735 A1 Aug. 2, 2012

Related U.S. Application Data

(62) Division of application No. 12/211,650, filed on Sep. 16, 2008, now Pat. No. 8,208,662.

(51) **Int. Cl.**
H04R 25/00 (2006.01)

(52) **U.S. Cl.** **381/174**; 381/191; 381/396; 381/398; 381/423; 381/175; 257/414; 257/415; 257/416; 257/417; 257/418; 257/429; 257/245; 257/254; 438/48; 438/49; 438/50

(58) **Field of Classification Search** 381/191, 381/396, 398, 399, 423, 174–175; 438/48–98; 257/414–419, 245, 254
See application file for complete search history.

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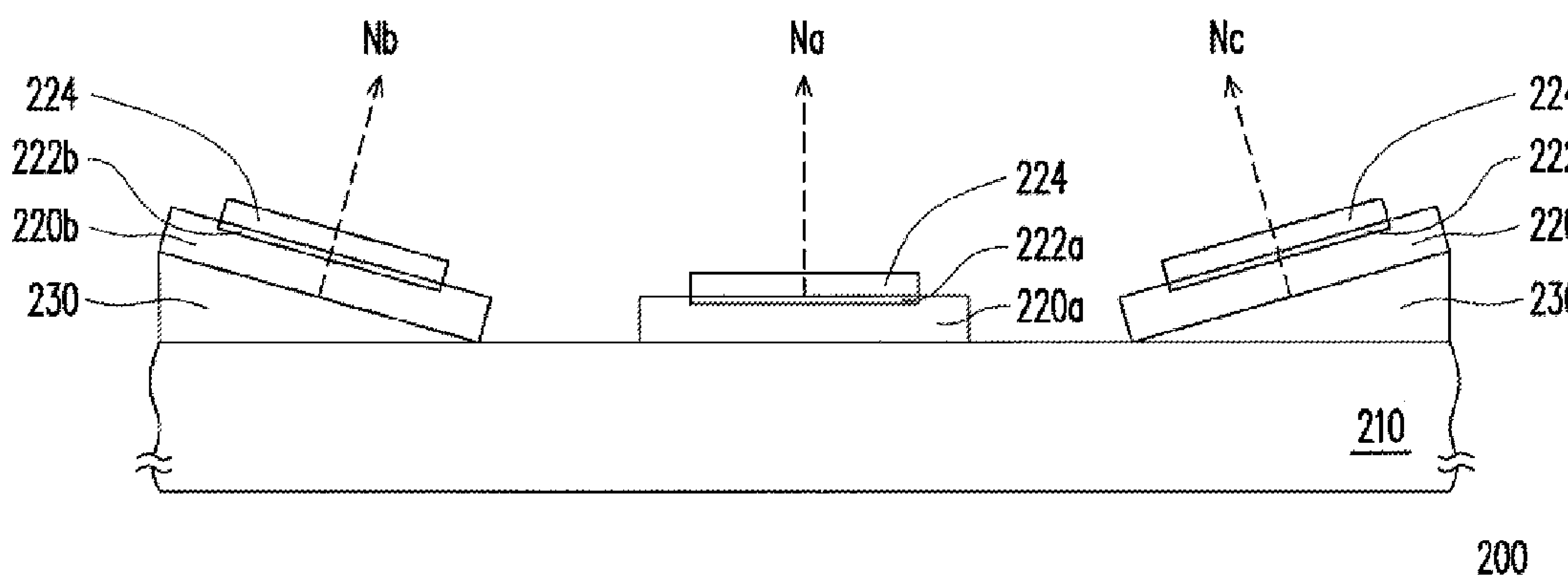
(57) **ABSTRACT**

A microelectromechanical system microphone package structure includes a base plate and a plurality of chips is provided. The plurality of chips are disposed on the base plate, wherein an active area of each of the chips is disposed with a microelectromechanical system microphone structure, each of the active areas comprises a normal line, and the normal lines of the chips are unparallel and nonorthogonal to each other.

3 Claims, 2 Drawing Sheets



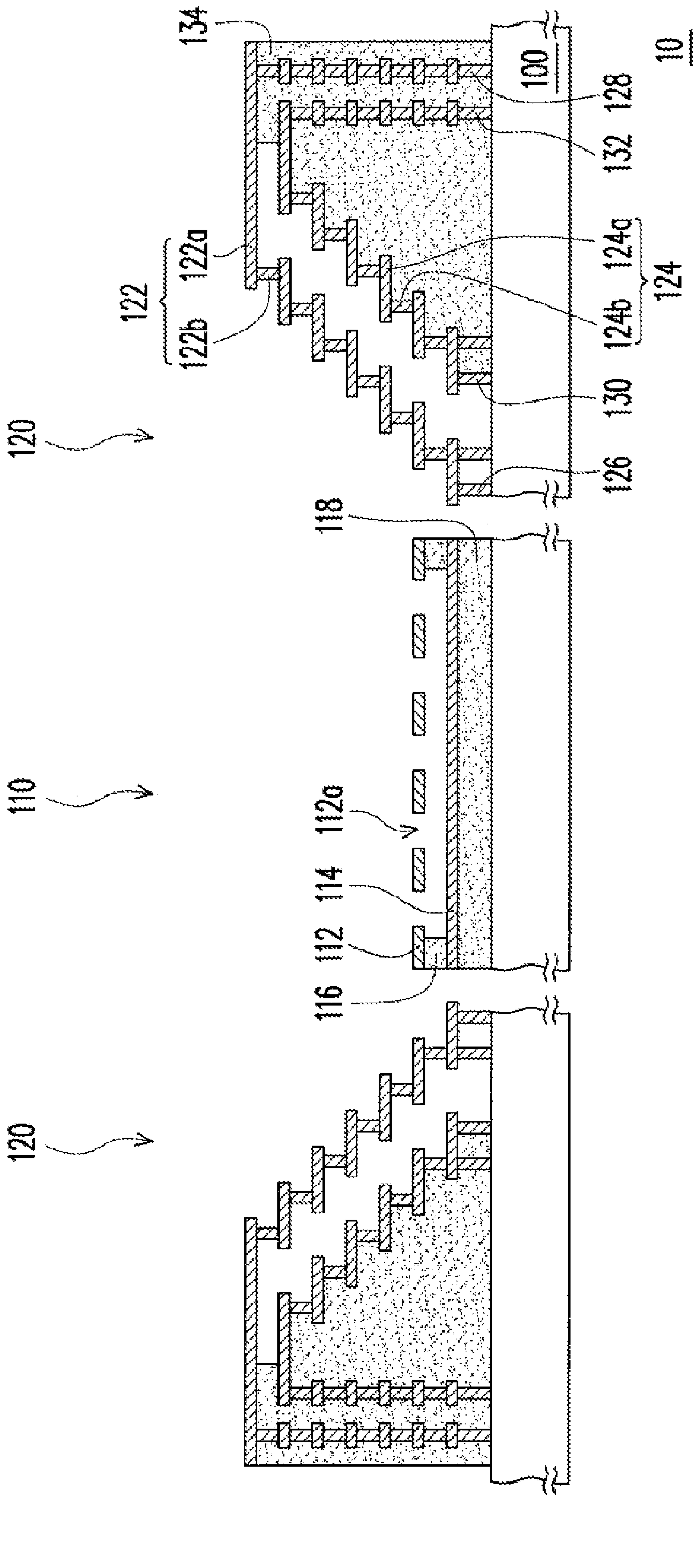

134
100
10
128
132
122
122a
122b
124a
124b
124
130
120
126
118
110
112a
114
112
116
120

FIG. 1

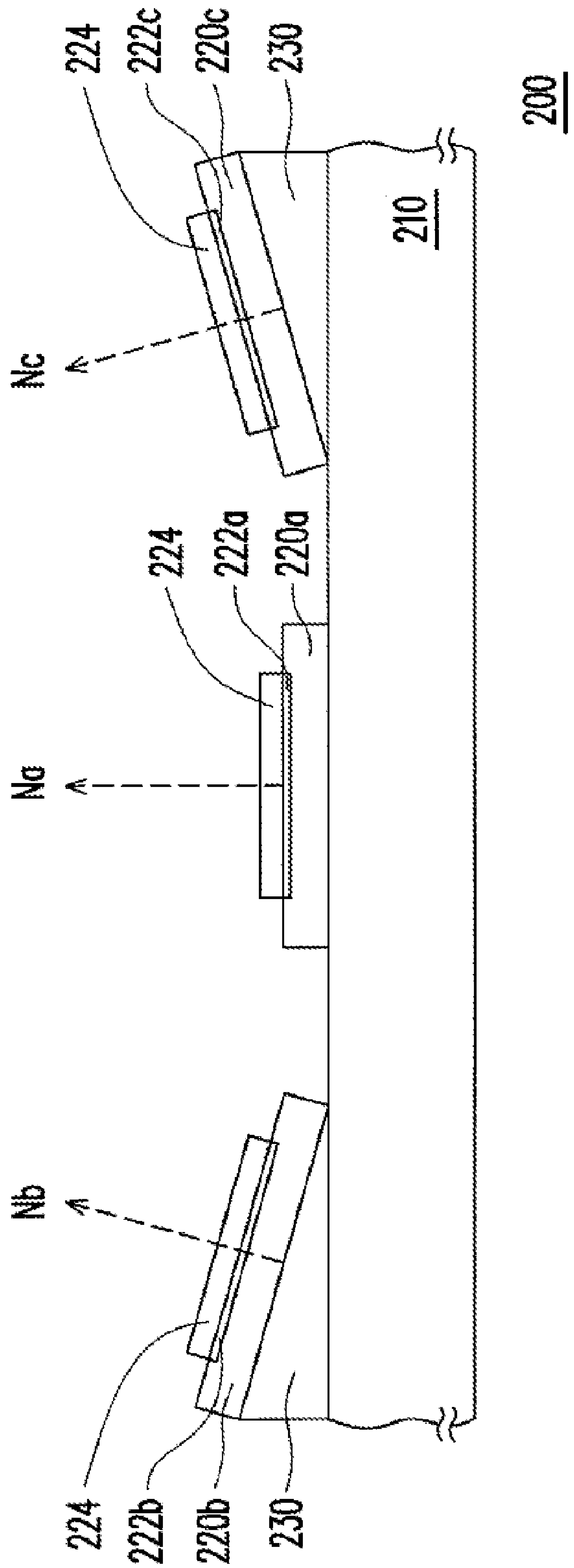

224
222c
220c
230
200
210
Nc
224
222a
220a
Na
Nb
224
222b
220b
230

FIG. 2

MICROELECTROMECHANICAL SYSTEM MICROPHONE PACKAGE STRUCTURE

CROSS-REFERENCE TO RELATED APPLICATION

The present application is a divisional application claiming benefit from a parent U.S. patent application bearing a Ser. No. 12/211,650 and filed Sep. 16, 2008, contents of which are incorporated herein for reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention generally relates to a semiconductor device, in particular, to a microelectromechanical system microphone package structure.

2. Description of Related Art

Microelectromechanical System Device (MEMS device) refers to a microelectromechanical device manufactured in a miniaturized package structure with a technology extremely similar to a technology for manufacturing an integrated circuit (IC). However, the MEMS device interacts with a surrounding environment in more manners than a conventional IC, such as interaction in mechanics, optics, or magnetic force. The MEMS device includes tiny electromechanical devices, such as an accelerometer, a switch, a capacitor, an inductor, and a microphone. The MEMS device manufactured with an MEMS technology has many advantages. For example, an MEMS microphone manufactured with the MEMS technology has features of light weight, small volume, and preferred signal quality. Therefore, the MEMS microphone gradually becomes the mainstream of microphones.

Generally speaking, the MEMS microphone has been improved both in reception efficiency and stability, and can provide clear and fluent voice quality either in a noisy environment or in high-speed movement. However, since a diaphragm for reception is a plane, phase noises are caused, i.e., a sounder and surrounding environmental noises may be heard by a receiver, so the receiver is interfered when understanding an audio message. On the contrary, a directional microphone is provided with a function of distinguish the direction of a sound source, which may enhance the intensity of sound in a specific direction and reduce the intensity of sound from other directions, so that the receiver may hear a clear and correct audio message. Therefore, along with the rapid development of personal electronic products such as mobile phones, personal digital assistants (PDAs), notebooks, and hearing aids, an MEMS microphone with a directional function is in urgent need in the industry.

SUMMARY OF THE INVENTION

The present invention is directed to a microelectromechanical system microphone package structure, which may distinguish sound sources in different directions.

The present invention provides a microelectromechanical system microphone package structure, which includes a base plate and a plurality of chips disposed on the base plate and having a plurality of respective active areas. Each of the chips is disposed with a microelectromechanical system microphone structure in the corresponding active area, and inclination angles of the chips are adjustable to have normal lines of the active areas of the chips unparallel and nonorthogonal to each other, thereby making the direction of a sound source distinguishable.

In an embodiment of the present invention, the normal lines extend toward the same point.

In an embodiment of the present invention, the microelectromechanical system microphone package structure further includes at least one holder, which is disposed between the base plate and the chips in order to adjust the inclination angles of the chips.

The microelectromechanical system microphone package structure in the present invention includes a plurality of unparallel and nonorthogonal planes for receiving acoustic waves. Therefore, the microelectromechanical system microphone package structure may distinguish the direction of a sound source, so as to increase the intensity of sound from a specific direction and reduce the intensity of sound from other directions based on calculation, thereby reducing phase noises. In other words, the microelectromechanical system microphone package structure has a directional function to reduce noises which may be heard by a receiver. Thus, the receiver may hear a clear and correct audio message.

BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings are included to provide a further understanding of the invention, and are incorporated in and constitute a part of this specification. The drawings illustrate embodiments of the invention and, together with the description, serve to explain the principles of the invention.

FIG. **1** is a schematic cross-sectional view of a microelectromechanical system microphone structure according to a first embodiment of the present invention.

FIG. **2** is a schematic cross-sectional view of a microelectromechanical system microphone package structure according to a second embodiment of the present invention.

DESCRIPTION OF THE EMBODIMENTS

Reference will now be made in detail to the present preferred embodiments of the invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts.

The First Embodiment

FIG. **1** is a schematic cross-sectional view of a microelectromechanical system microphone structure according to a first embodiment of the present invention.

Referring to FIG. **1**, the microelectromechanical system microphone structure **10** includes a substrate **100**, a first device **110**, and a second device **120**.

The first device **110** is disposed on the substrate **100**, and includes a first upper electrode **112**, a first lower electrode **114**, a dielectric layer **116**, and a dielectric layer **118**. In this embodiment, the first upper electrode **112** includes, for example, a plurality of holes **112*a***. Therefore, the first upper electrode **112** is a mesh electrode, and the material thereof may be polysilicon, polysilicon metal, aluminum, tungsten, copper, titanium, or other conductive materials. The first lower electrode **114** is disposed between the first upper electrode **112** and the substrate **100**, which may be, for example, a whole piece of electrode, and the material may be polysilicon, polysilicon metal, aluminum, tungsten, copper, titanium, or other conductive materials. In this embodiment, the dielectric layer **116** is partially disposed between the first upper electrode **112** and the first lower electrode **114**, so that a part of the first upper electrode **112** is suspended. The dielectric layer **118** is disposed between the whole first lower electrode **114** and the substrate **100**. Of course, in other embodiments (not shown), the dielectric layer **118** may also be partially disposed between the first lower electrode **114** and the substrate **100**, so that a part of the first lower electrode **114** is suspended. Furthermore, in the present invention, the first upper electrode and the first lower electrode are not limited in configuration and may be mesh electrodes, stripped electrodes, whole pieces of electrodes, and electrodes in other forms.

The second device **120** is disposed on the substrate **100** and surrounding the first device **110**. In other words, the second device **120**, for example, surrounds the first device **110**. The second device **120** includes a second upper electrode **122** and a second lower electrode **124**. The second upper electrode **122** is a diaphragm, and includes a plurality of first conductive layers **122***a* and a plurality of first plugs **122***b*. The first conductive layers **122***a* are arranged in steps, and each of the first plugs **122***b* is disposed between the adjacent first conductive layers **122***a*. The second lower electrode **124** is disposed between the second upper electrode **122** and the substrate **100**, and includes a plurality of second conductive layers **124***a* and a plurality of second plugs **124***b*. The second conductive layers **124***a* are arranged in steps, and each of the second plugs **124***b* is disposed between the adjacent second conductive layers **124***a*. The material of the first conductive layers **122***a* and the second conductive layers **124***a* may be polysilicon, polysilicon metal, aluminum, tungsten, copper, titanium, or other conductive materials, and the material of the first plugs **122***b* and the second plugs **124***b* may be copper, tungsten, aluminum, molybdenum, gold, platinum, or an alloy thereof. In this embodiment, the first conductive layers **122***a* are, for example, parallel to the second conductive layers **124***a*. Moreover, a horizontal distance between a first conductive layer **122***a* and the first device **110** is increased as a height of the first conductive layer **122***a* is increased, and a horizontal distance between a second conductive layer **124***a* and the first device **110** is increased as a height of the second conductive layer **124***a* is increased. In other words, the second upper electrode **122** and the second lower electrode **124** are similar in structure and parallel to each other. Furthermore, in other embodiments (not shown), the first conductive layers and the second conductive layers may also include holes, so as to increase flexibility and acoustic wave transmission capacity of the second upper electrode and the second lower electrode. Furthermore, the present invention does not limit the number of the first conductive layers in the second upper electrode and the number of the second conductive layers in the second lower electrode. In other embodiments, the second upper electrode may include another number of first conductive layers, and the second lower electrode may also include another number of second conductive layers.

In this embodiment, plugs **126**, a plug **128**, a plug **130**, and a plug **132** are further disposed between the substrate **100** and the lowermost first conductive layer **122***a*, the uppermost first conductive layer **122***a*, the lowermost second conductive layer **124***a*, and the uppermost second conductive layer **124***a*, respectively, so as to stabilize the structures of the second upper electrode **122** and the second lower electrode **124**. Moreover, in this embodiment, the second device **120** further includes a dielectric layer **134** which is, for example, disposed between the uppermost first conductive layer **122***a* and the substrate **100** and between the uppermost second conductive layer **124***a* and the substrate **100**, so as to further stabilize the structures of the second upper electrode **122** and the second lower electrode **124**. In addition, the dielectric layer **134** is further disposed between the second lower electrode **124** and the substrate **100**, so as the second lower electrode **124** is not able to vibrate or a vibration extent of the second lower electrode **124** is much smaller than that of the second upper electrode **122**. Furthermore, in other embodiments, only the plugs or dielectric layer is disposed between the uppermost first conductive layer and the substrate and between the uppermost second conductive layer and the substrate, which is not limited in the present invention.

In this embodiment, the second upper electrode **122** and the second lower electrode **124** of the second device **120** form an included angle with the substrate **100**, so that the second upper electrode **122** of the second device **120** faces the first upper electrode **112** of the first device **110**. In other words, the normal line of the second upper electrode **122** is unparallel and nonorthogonal to the normal line of the first upper electrode **112**, so that the microelectromechanical system microphone structure **10** includes a plurality of planes for receiving acoustic waves. In this manner, the microelectromechanical system microphone structure **10** may distinguish the direction of a sound source. Furthermore, in this embodiment, for example, the first device **110** is surrounded by two second devices **120**, but the present invention is not limited thereto. In other embodiments, the microelectromechanical system microphone structure may also include one second device or another number of second devices.

In this embodiment, the microelectromechanical system microphone structure includes the first device and the second device. The first device includes the upper and lower electrodes parallel to the substrate, and the second device includes the upper and lower electrodes in a stepped form. The first device and the second device constitute a plurality of planes for receiving acoustic waves, so that the microelectromechanical system microphone structure may distinguish the direction of a sound source, so as to increase the intensity of sound from a specific direction and reduce the intensity of sound from other directions based on calculation, thereby reducing phase noises. That is to say, the microelectromechanical system microphone structure has a directional function to reduce noises which may be heard by a receiver. Thus, the receiver may hear a clear and correct audio message. Therefore, the microelectromechanical system microphone structure may be widely used in personal electronic products such as mobile phones, personal digital assistants (PDAs), notebooks, and hearing aids, so as to improve communication between the user and the receiver.

The Second Embodiment

FIG. **2** is a schematic cross-sectional view of a microelectromechanical system microphone package structure according to a second embodiment of the present invention.

Referring to FIG. **2**, the microelectromechanical system microphone package structure **200** includes a base plate **210**, a plurality of chips **220***a*, **220***b*, and **220***c*, and holders **230**. The chips **220***a*, **220***b*, and **220***c* are disposed on the base plate **210**, and for example, the chip **220***a* is surrounded by the chips **220***b* and **220***c*.

The chips **220***a*, **220***b*, and **220***c* respectively have active areas **222***a*, **222***b*, and **222***c*, and each of the active areas **222***a*, **222***b*, and **222***c* is provided with a microelectromechanical system microphone structure **224**. In other words, the chips **220***a*, **220***b*, and **220***c* are MEMS microphone chips. The structure of the microelectromechanical system microphone structure **224** may be similar to the structure of the first device **110** in the first embodiment or other structures, which is not limited in the present invention.

In this embodiment, the active area **222***a* of the chip **220***a* is, for example, parallel to the surface of the base plate **210**. The holders **230** are disposed between the chips **220***b* and **220***c* and the base plate **210**, so as to adjust inclination angles of the chips **220***b* and **220***c*, so that the active areas **222***b* and **222***c* of the chips **220***b* and **220***c* face the active area **222***a* of the chip **220***a*. In other words, in the microelectromechanical system microphone package structure **200**, the active areas **222***a*, **222***b*, and **222***c* respectively have normal lines Na, Nb, and Nc, which are unparallel and nonorthogonal to each other. The normal lines Na, Nb, and Nc, for example, extend toward the same point. In other words, the microelectromechanical system microphone package structure **200** includes a plurality of planes for receiving acoustic waves, so as to distinguish the direction of a sound source.

It should be noted that, this embodiment takes three chips **220***a*, **220***b*, and **220***c* as an example, but the present invention does not limit the number of the chips. In other embodiments, the microelectromechanical system microphone package structure may also include two chips or another number of chips.

In this embodiment, the positions of the chips **220***b*, and **220***c* are adjusted in a package level, so as the normal lines Na, Nb, and Nc of the active areas of the plurality of chips are unparallel and nonorthogonal to each other. In this manner, the microelectromechanical system microphone package structure includes a plurality of planes for receiving acoustic waves to distinguish the direction of a sound source, so as to increase the intensity of sound from a specific direction and reduce the intensity of sound from other directions based on calculation, thereby reducing phase noises. In other words, the microelectromechanical system microphone package structure has a directional function to reduce noises which may be heard by a receiver. Thus, the receiver may hear a clear and correct audio message. Therefore, the microelectromechanical system microphone structure may be widely used in personal electronic products such as mobile phones, personal digital assistants (PDAs), notebooks, and hearing aids, so as to improve communication between the user and the receiver.

In view of the above, the microelectromechanical system microphone package structure in the present invention includes a plurality of unparallel and nonorthogonal planes for receiving acoustic waves. Therefore, the microelectromechanical system microphone package structure may distinguish the direction of a sound source, so as to increase the intensity of sound from a specific direction and reduce the intensity of sound from other directions based on calculation, thereby reducing phase noises. In other words, the microelectromechanical system microphone package structure has a directional function to reduce noises which may be heard by a receiver. Thus, the receiver may hear a clear and correct audio message. Therefore, the microelectromechanical system microphone package structure may be widely used in personal electronic products such as mobile phones, personal digital assistants (PDAs), notebooks, and hearing aids, so as to improve communication between the user and the receiver.

It will be apparent to those skilled in the art that various modifications and variations can be made to the structure of the present invention without departing from the scope or spirit of the invention. In view of the foregoing, it is intended that the present invention cover modifications and variations of this invention provided they fall within the scope of the following claims and their equivalents.

What is claimed is:

1. A microelectromechanical system microphone package structure, comprising:

a base plate; and

a plurality of chips, disposed on the base plate and having a plurality of respective active areas, wherein each of the chips is disposed with a microelectromechanical system microphone structure in the corresponding active area, and inclination angles of the chips are adjustable to have normal lines of the active areas of the chips unparallel and nonorthogonal to each other, thereby making a direction of a sound source distinguishable.

2. The microelectromechanical system microphone package structure according to claim **1**, wherein the normal lines extend toward the same point.

3. The microelectromechanical system microphone package structure according to claim **1**, further comprising at least one holder, disposed between the base plate and the chips in order to adjust the inclination angles of the chips.

* * * * *